

ABSTRACT

RESIN SEALING TYPE SEMICONDUCTOR DEVICE AND
METHOD OF MAKING THE SAME

A resin sealing type semiconductor device includes a semiconductor element having electrodes and a fixing surface, and a heat radiator for cooling the semiconductor element. The heat radiator includes a mounting surface on which the semiconductor element is mounted. A bonding layer is formed on the mounting surface between the semiconductor element and the heat radiator. The planar dimension of the bonding layer is smaller than that of the fixing surface of the semiconductor element. The semiconductor element adheres to the bonding layer through an adhesive layer. A resin package seals the semiconductor element, the heat radiator, and parts of leads and wires.

Figure 1